

Title (en)

Method of manufacturing a MICROELECTRONIC INTERCONNECT DEVICE COMPRISING LOCALISED CONDUCTIVE PINS

Title (de)

Herstellungsverfahren für eine MIKROELEKTRONISCHE VERBINDUNGSEINRICHTUNG MIT LOKALISIERTEN LEITFÄHIGEN PINS

Title (fr)

Procédé de fabrication d'un DISPOSITIF MICROELECTRONIQUE D'INTERCONNEXION A TIGES CONDUCTRICES LOCALISEES

Publication

EP 1719173 A1 20061108 (FR)

Application

EP 05717721 A 20050224

Priority

- FR 2005050123 W 20050224
- FR 0450349 A 20040225

Abstract (en)

[origin: FR2866753A1] Fabrication of conducting pins (310) endowed with one or more conductor contacts (302), each coming into contact with an electronic component contact, comprises: (a) deposition of a masking layer on a component; (b) formation of holes in the masking layer; (c) filling these holes with a conducting material to form the conducting pins; (d) removing the masking layer. An independent claim is also included for micro-electronic devices obtained by this method.

IPC 8 full level

H01L 21/60 (2006.01); **H01L 23/00** (2006.01); **H01L 23/485** (2006.01); **H01L 23/498** (2006.01)

CPC (source: EP US)

H01L 23/49811 (2013.01 - EP US); **H01L 24/05** (2013.01 - EP US); **H01L 24/11** (2013.01 - EP US); **H01L 24/12** (2013.01 - EP US); **H01L 24/16** (2013.01 - EP US); **H01L 2224/0401** (2013.01 - EP US); **H01L 2224/04042** (2013.01 - EP US); **H01L 2224/05599** (2013.01 - EP US); **H01L 2224/114** (2013.01 - EP US); **H01L 2224/1147** (2013.01 - EP US); **H01L 2224/116** (2013.01 - EP US); **H01L 2224/13078** (2013.01 - EP US); **H01L 2224/13099** (2013.01 - EP US); **H01L 2224/48463** (2013.01 - EP US); **H01L 2224/83192** (2013.01 - EP US); **H01L 2224/85399** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01022** (2013.01 - EP US); **H01L 2924/01028** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01057** (2013.01 - EP US); **H01L 2924/01058** (2013.01 - EP US); **H01L 2924/01074** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US)

Citation (search report)

See references of WO 2005086232A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

FR 2866753 A1 20050826; **FR 2866753 B1 20060609**; EP 1719173 A1 20061108; US 2007166978 A1 20070719; US 7563703 B2 20090721; WO 2005086232 A1 20050915

DOCDB simple family (application)

FR 0450349 A 20040225; EP 05717721 A 20050224; FR 2005050123 W 20050224; US 59041205 A 20050224